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P/4076-71

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of

Yam Mo Wong et al.

Date: June 17, 2005

Serial No.: 10/790,969

Group Art Unit: 2811

Filed: March 1, 2004

Examiner: Theresa T. Doan

For: MULTIPLE-BALL WIRE BONDS

Mail Stop Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

RESPONSE

Sir:

Responsive to the Restriction Requirement mailed June 1, 2005, Applicant provisionally elects group I, claims 1-12, drawn to the method, with traverse.

In support of the Requirement for Restriction, the Examiner suggests an alternative method for forming the wire bond bonding a wire to a connection pad of an electronic device of claim 13, by first forming a second bump on a first bump ball and then forming them together on a connection pad, rather than in each instance forming each bump ball on the connection pad in the first instance of their formation. Reconsideration of the Requirement is requested, because the alternative does not comply with the claim language and in addition, it is technically unsound.

Method claim 1 requires:

forming a first bump ball on the connection pad...

forming a second bump on the connection pad...

Correspondingly, device claim 13 recites:

a first bump ball formed on the connection pad...

a second bump ball formed on the connection pad...

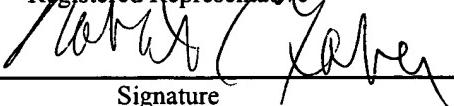
In both of claims 1 and 13, the respective bump balls are formed on a connection pad, not formed elsewhere and thereafter moved to a connection pad, and in particular, not first forming the second bump ball on the first bump ball before forming each of them on a connection pad. Rather, both bump balls are formed on the connection pad, as claims 1 and 13 recite. That the second bump ball may be formed on the first bump ball is not excluded by either of claims 1 and 13. But that cannot avoid the recital in those claims that the first and the second bump balls are formed on the connection pad. The Examiner's proposed alternative method excludes the formation of the second ball on the connection pad.

Without intending to limit the scope of claims 1 and 13, and as an example, page 1, lines 21-26 of the specification note that bump balls are formed and bonded to connection pads by a solid phase welding process.

In order to transfer a previously formed bump ball to another surface, the bump balls must be scraped off the first surface and then reattached to a second surface, as of connection pad, by some means. This Examiner's suggestion of an alternative method is not practical, is inconsistent with the claims and the alternative process suggested as described is not amenable to automated production and is not practical.

It is believed that the process claimed cannot be used to make any other and material different product and that the product claimed cannot be made by another and materially different process. Consequently, withdrawal of the Restriction Requirement is requested.

I hereby certify that this correspondence is being deposited with the United States Postal Service with sufficient postage as First Class Mail in an envelope addressed to: Mail Stop Amendment, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on June 17, 2005:

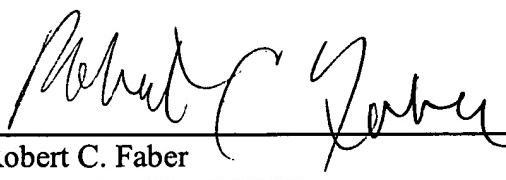
Robert C. Faber
Name of applicant, assignee or
Registered Representative


Signature

June 17, 2005

Date of Signature

Respectfully submitted,



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